


**Packaging structure of image sensor and method thereof**

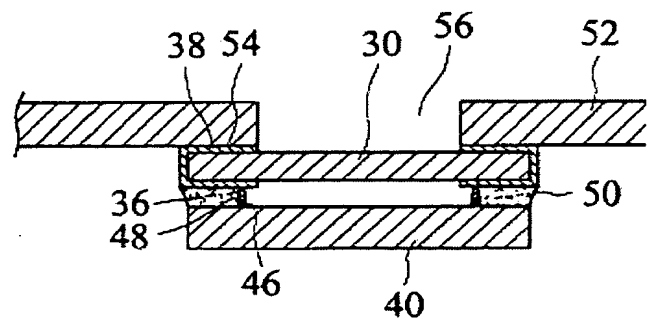
(A)

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 US2002096782 (A)**Abstract of TW459355**

The present invention is a packaging structure of image sensor and method thereof, wherein the image sensor chip is packaged on the light-transmission layer by the way of flip-chip, which comprises: a light transmission layer on which a signal input terminal and signal output terminal are disposed, wherein the signal input terminal is used for electrically connecting the printed circuit board; an image sensor chip which is electrically connected to the input signal terminal of the light transmission layer in flip-chip fashion, wherein the image sensor receives the image signal through the light transmission layer, converts the image signal into electrical signal, and transmits same to the printed circuit board from the input signal terminal of the light transmission layer, whereby the package cost of the image sensor is greatly reduced and the process is simplified.



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